Amendments to the Claims:

The following listing of claims replaces all prior versions, and listings, of claims in the application:

<u>Listing of Claims</u>:

1. (currently amended) A process for producing an organic-inorganic hybrid glassy material, the process comprising the sequential steps of:

producing a gel body by a sol-gel method in which at least one kind of a silicon alkoxide containing a phenyl group is used as a sol-gel raw material , and in which only an acid is used as a catalyst of the sol-gel method;

drying the gel body to obtain a dry gel;

melting the dry gel by heating at a temperature not lower than softening temperature of the dry gel and not higher than 400°C of from 100°C to 300°C into a melt; and

aging the melt at a temperature of from 30°C to 400°C for a period of time of 5 minutes or longer.

wherein a structure of the gel body contains a unit represented by the formula $Ph_nSiO_{(4\cdot n)/2}$, where Ph represents a phenyl group and n represents a natural number selected from 1, 2 and 3.

2-22. (canceled)

23. (currently amended) A process for producing an organic-inorganic hybrid glassy material, the process comprising the sequential steps of:

producing a gel body by a sol-gel method in which at least one kind of a silicon alkoxide containing a phenyl group is used as a sol-gel raw material, and in which only an acid is used as a catalyst of the sol-gel method;

drying the gel body to obtain a dry gel;

mixing the dry gel with a substance obtained by a non-aqueous acid-base reaction method to prepare a mixture;

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melting the mixture by heating at a temperature not lower than softening temperature of the dry gel and not higher than 400°C of from 100°C to 300°C into a melt; and

aging the melt at a temperature of from 30°C to 400°C for a period of time of 5 minutes or longer.

24. (previously presented) A process for producing an organic-inorganic hybrid glassy material as claimed in claim 23, wherein the gel body produced by the solgel method contains RSiO_{3/2} or R₂SiO, wherein R represents a phenyl group.

25. (previously presented) A process for producing an organic-inorganic hybrid glassy material as claimed in claim 23 or 24, wherein the substance obtained by the non-aqueous acid-base reaction method contains R_2SiO , wherein R represents a methyl or ethyl group, P_2O_5 and SnO.

26-29. (canceled)

30. (currently amended) A process for producing an organic-inorganic hybrid glassy material, the process comprising the sequential steps of:

producing a gel body by a sol-gel method in which a phenyltrialkoxysilane and a second silane are used as sol-gel raw materials, wherein the second silane is selected from the group consisting of alkylalkoxysilanes and diphenyldialkoxysilanes;

drying the gel body to obtain a dry gel;

melting the dry gel by heating at a temperature not lower than softening temperature of the dry gel and not higher than 400°C of from 100°C to 300°C into a melt; and

aging the melt at a temperature of from 30°C to 400°C for a period of time of 5 minutes or longer .

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wherein a ratio of the phenyltrialkoxysilane to the second silane by mol percent based on a total mol number of the phenyltrialkoxysilane and the second silane is from 7:3 to 9:1.

- 31. (previously presented) A process according to claim 30, wherein:

 the phenyltrialkoxysilane is phenyltriethoxysilane; and
 the diphenyldialkoxysilane is diphenyldiethoxysilane or the
 alkylalkoxysilane is selected from the group consisting of methyltriethoxysilane,
 dimethyldiethoxysilane, diethyldiethoxysilane, and ethyltriethoxysilane.
- 32. (previously presented) A process according to claim 30, wherein: the phenyltrialkoxysilane is phenyltriethoxysilane; and the second silane is a dialkyldialkoxysilane.
- 33. (previously presented) A process according to claim 32, wherein the dialkyldialkoxysilane is dimethyldiethoxysilane or diethyldiethoxysilane.
- 34. (previously presented) A process according to claim 30, wherein: the phenyltrialkoxysilane is phenyltriethoxysilane; and the second silane is a diphenyldialkoxysilane.
- 35. (previously presented) A process according to claim 34, wherein the diphenyldialkoxysilane is diphenyldiethoxysilane.
- 36. (new) A process according to claim 1, wherein the acid is hydrochloric acid or acetic acid.
- 37. (new) A process according to claim 23, wherein the acid is hydrochloric acid.